

FULL 50-60Hz RECTIFICATION BRIDGE**MAIN PRODUCT CHARACTERISTICS**

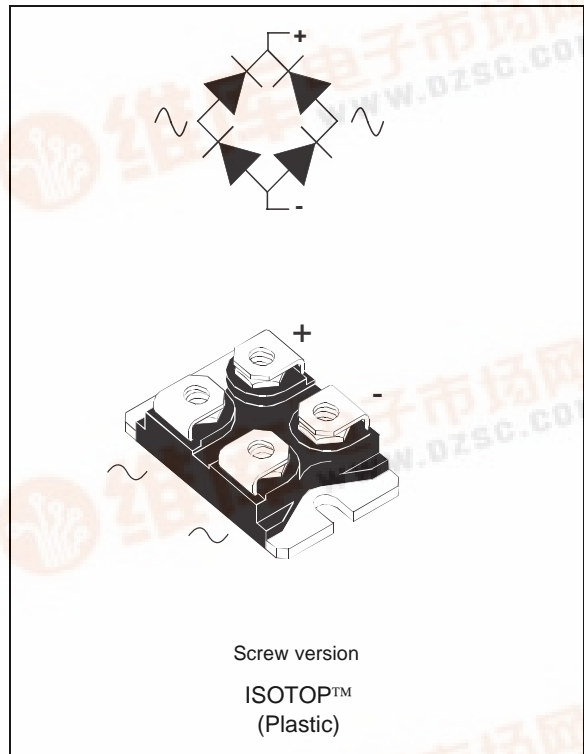
$I_F(AV)$	35A
V_{RRM}	600V
V_F (max)	1.3V

FEATURES AND BENEFITS

- COMPACT ISOTOP DESIGN COMPATIBLE WITH FAST DIODES, TRANSISTORS AND PASSIVE COMPONENTS.
- EXCELLENT THERMAL TRANSFER JUNCTION TO HEATSINK
- UL PENDING

DESCRIPTION

The Bridges series from SGS-THOMSON has been designed to allow a better standardization of packages on boards principally designed with ISOTOP packages. The insulated package of the bridge will be able to sit on heatsink with other components. Single phase and 3-phase high power SMPS, UPS, MOTOR DRIVES and WELDING equipment will primarily find advantage in these industry package products.

PRELIMINARY DATASHEET**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (per diode unless specified)**

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		600	V
V_{RSM}	Non repetitive peak reverse voltage		600	V
$I_F(AV)$ total	Average forward current	$T_c=80^\circ\text{C}$ Sinus	35	A
I_{FSM}	Surge non repetitive forward current 50Hz JEDEC method		300	A
$I^2.t$	Fusing		660	A ² .s
T_{stg}	Storage temperature range		- 65 to + 150	°C
T_j	Max. operating junction temperature		150	°C
P_{max} total	Total power dissipation		50	W

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BF3506TV

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
Rth (j-c) total	Junction to case	0.5	°C/W

ELECTRICAL CHARACTERISTICS (Per diode)

STATIC CHARACTERISTICS

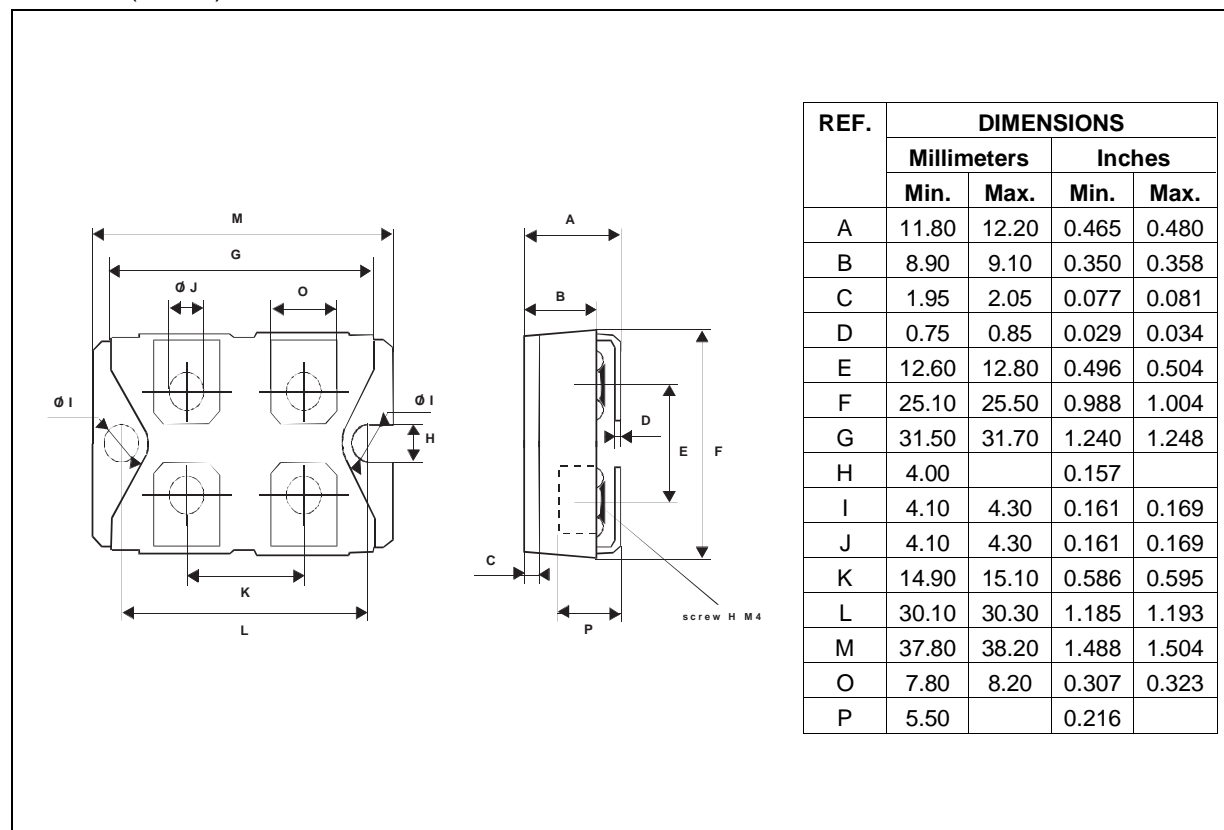
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I _R *	Reverse leakage current	V _R = 0.8 V _{RRM} δ < 2% tp = 5ms	T _j = 25°C		10	μA
			T _j = 125°C		0.2	mA
V _F **	Forward voltage drop	I _F = 35 A δ < 2% tp = 380μs	T _j = 25°C		1.4	V
			T _j = 125°C		1.3	V

Pulse test : * tp = 5 ms, duty cycle < 2 %

** tp = 380 μs, duty cycle < 2 %

For one diode: Pcond = 1.02 × I_{F(AV)} + 0.008 × I_{F(RMS)}² and T_j = Pcond × 4 × Rth(j-c) + T_c

PACKAGE DATA (millimeter)
ISOTOP (Plastic)



Cooling method : C

Marking : Type number

Weight : 28 g. (without screws)

Electrical isolation : 2500V_(RMS)

Capacitance : < 45 pF

Inductance : < 5 nH

- Recommended torque value : 1.3 N.m (MAX 1.5 N.m) for the 6 x M4 screws. (2 x M4 screws recommended for mounting the package on the heatsink and the 4 screws given with the screw version).
- The screws supplied with the package are adapted for mounting on a board (or other types of terminals) with a thickness of 0.6 mm min and 2.2 mm max.

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